

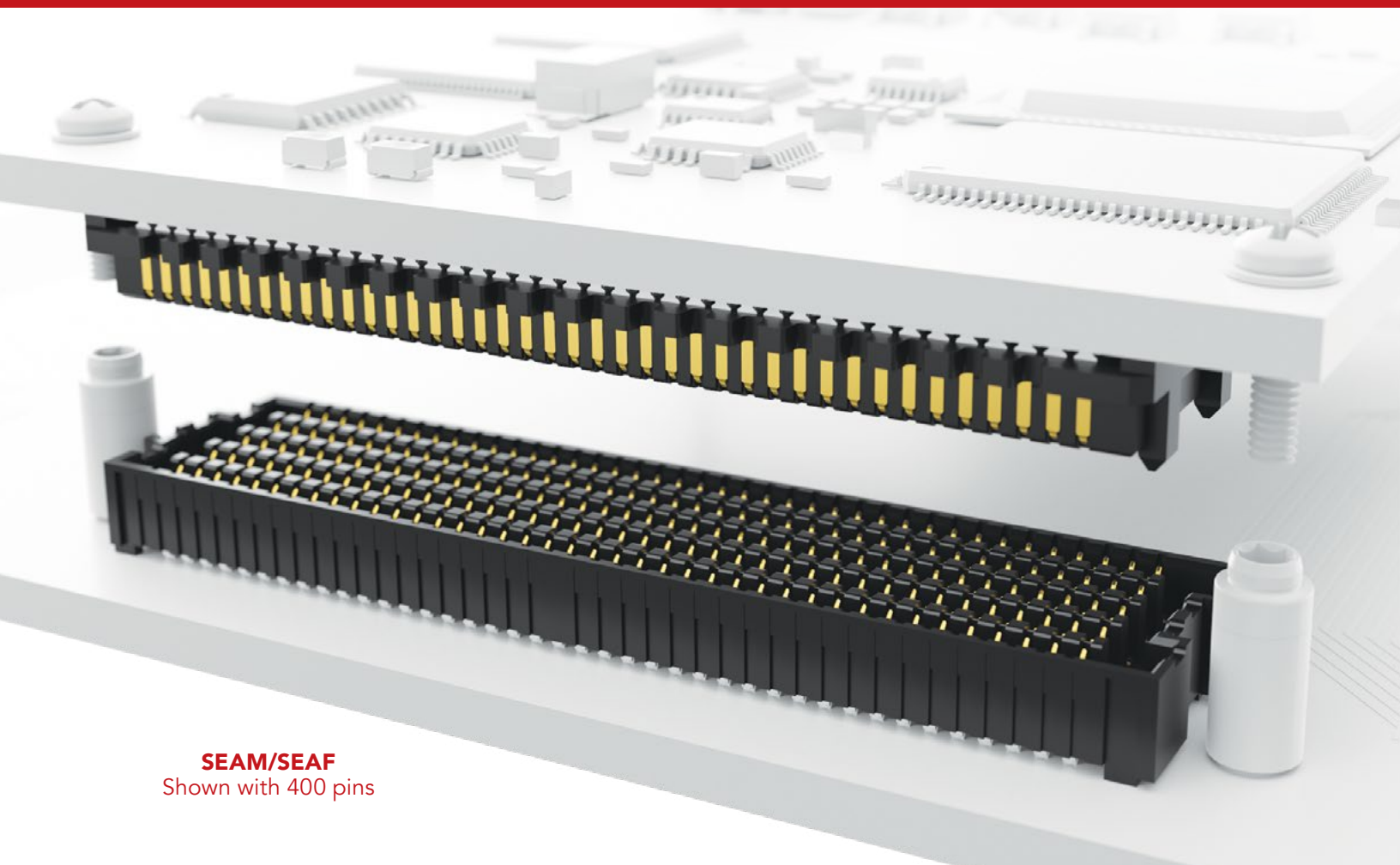


HIGH-DENSITY **ARRAYS**



HIGH-DENSITY ARRAYS

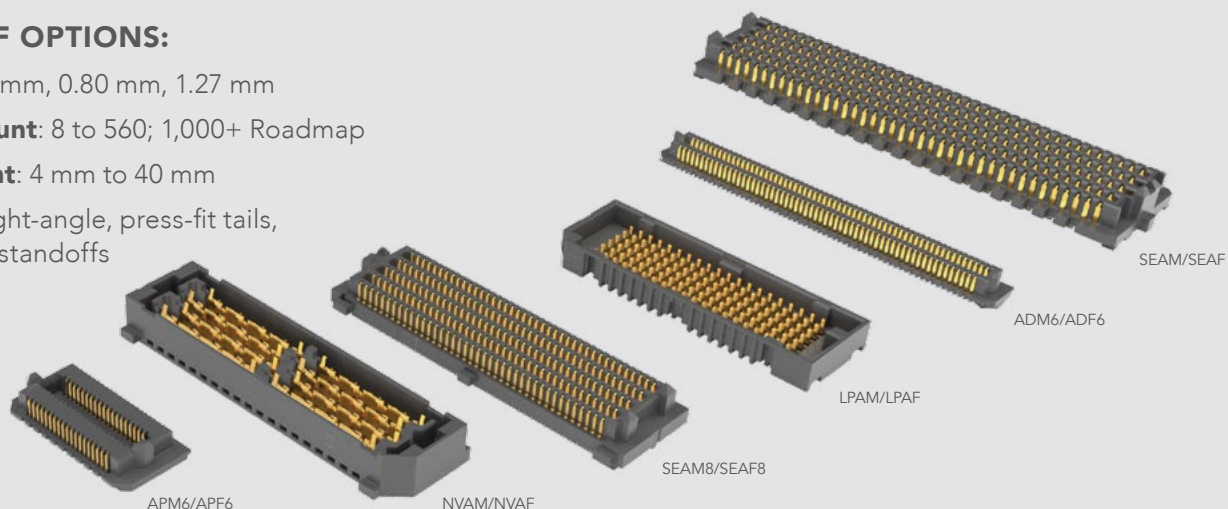
EXTREME PERFORMANCE • OPEN-PIN-FIELD • LOW-PROFILE



SEAM/SEAF
Shown with 400 pins

VARIETY OF OPTIONS:

- **Pitch:** 0.635 mm, 0.80 mm, 1.27 mm
- **Pin/Pair Count:** 8 to 560; 1,000+ Roadmap
- **Stack Height:** 4 mm to 40 mm
- **Options:** Right-angle, press-fit tails, 85 Ω tuned, standoffs



EXTREME PERFORMANCE ARRAYS

- 4.0 Tbps aggregate data rate - 9 IEEE 400G channels
- Two points of contact ensure a more reliable connection
- 112 fully shielded differential pairs per square inch
- Extremely low crosstalk (to 40 GHz) and incredibly tight impedance control
- Minimal variance in data rate as stack height increases
- Utilizes 40% less space with the same data throughput as compared to traditional arrays
- Terminal with latching available to mate with NovaRay® cable (NVAM-C)

NOVARAY®

NRZ	PAM4
56 Gbps	112 Gbps

NVAM/NVAF



SureWare™ guide post standoff (GPSO) assists with "blind mate" and misalignment mitigation



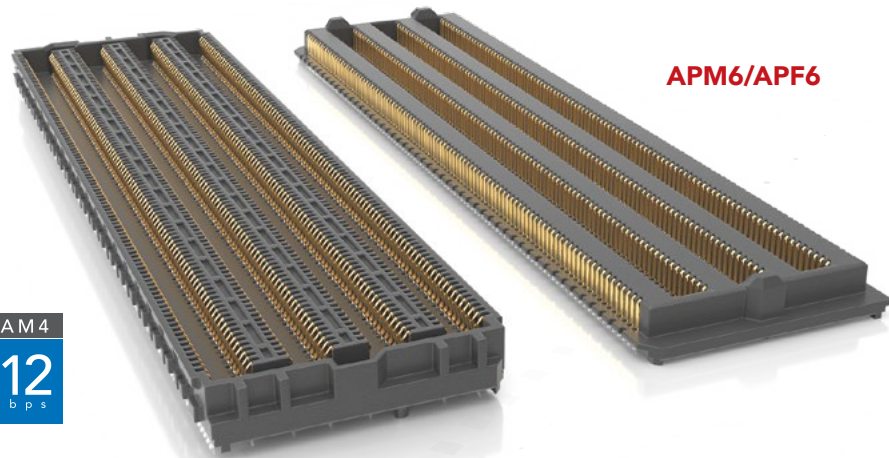
Mating assembly with 34 AWG Eye Speed® ultra low skew twinax cable

HIGH-PERFORMANCE ARRAYS

- Flexible open-pin-field and cost optimized, extreme performance solution
- Low-profile 5 mm stack height and up to 10 mm
- 0.635 mm pitch
- Four row design with up to 400 total pins; roadmap to 1,000+ pins
- Data rate compatible with PCIe® 5.0 and 100 GbE
- Cable assembly in development

ACCELERATE®HP

NRZ	PAM4
56 Gbps	112 Gbps



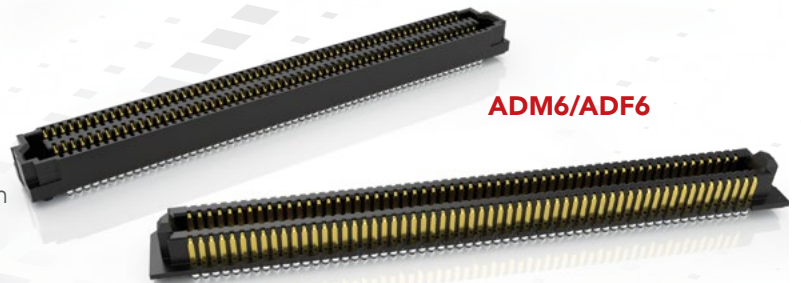
APM6/APF6

HIGH-DENSITY ARRAYS

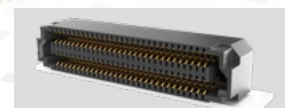
- Up to 400 I/Os in a 4-row, open-pin-field design
- 0.635 mm pitch Edge Rate® contacts
- Low profile 5 mm stack height and slim 5 mm width
- PCIe® 5.0 capable
- Compatible with mPOWER® for a power/signal solution
- Other stack heights in development

ACCELERATE®HD

PAM4
56 Gbps



ADM6/ADF6

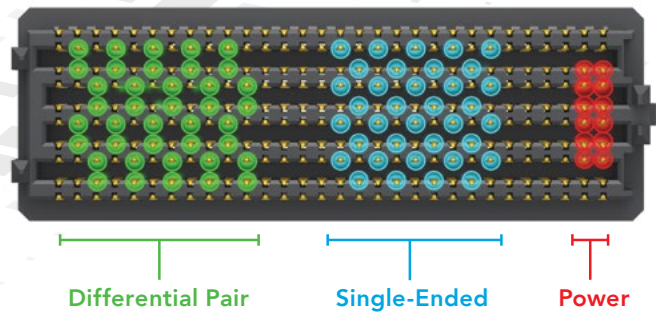


Right-angle in development (ADF6-RA)

1.27 mm PITCH ARRAYS

- Maximum grounding and routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance
- 7 mm to 40 mm stack heights; right-angle available
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel and InfiniBand™
- Standards: VITA and PISMO™ 2
- Compatible with mPOWER® (UMPT/UMPS) for power/signal flexibility

OPEN-PIN-FIELD FLEXIBILITY

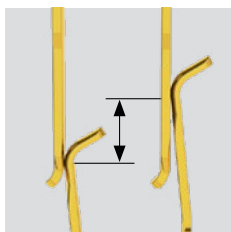


SEARRAY™

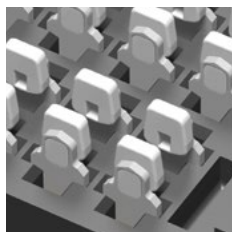
NRZ	PAM4
28 Gbps	56 Gbps



SEAM-RA



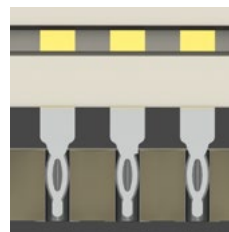
1.12 mm (.044")
contact wiper



Solder charge terminations
(IPC-A-610F & IPC J-STD-001F Class 3)



Elevated stack heights
available (SEAR)



Press-fit tails available
(SEAMP/SEAFP)



Jack screw
standoffs (JSO)

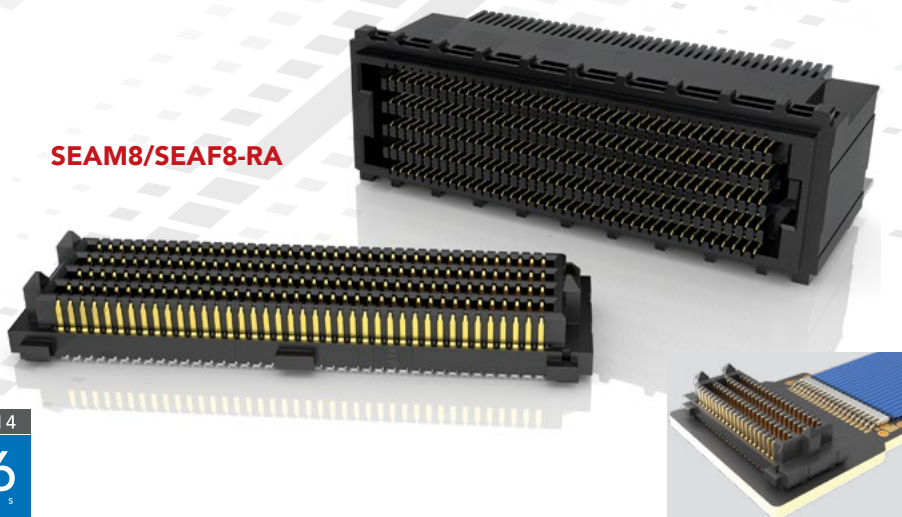
HIGH-DENSITY 0.80 mm PITCH ARRAYS

- 2x the density of 1.27 mm pitch arrays
- Up to 500 Edge Rate® contacts
- 7 mm and 10 mm stack heights
- Lower insertion/withdrawal forces
- Solder charge terminations for a secure connection to board
- Compatible with mPOWER® for power/signal flexibility

SEARRAY™.8mm

NRZ	PAM4
28 Gbps	56 Gbps

SEAM8/SEAF8-RA



Mating assembly with
34 AWG micro ribbon
coax cable (ESCA)

LOW PROFILE ARRAYS

- Up to 400 total pins in 4, 6 or 8 rows
- 4 mm, 4.5 mm and 5 mm stack heights
- 1.27 mm pitch dual beam contacts
- Compatible with mPOWER® for power/signal flexibility
- Press-in or threaded standoffs available to assist with unmating (JSO)

LPARRAY™

NRZ	PAM4
28 Gbps	56 Gbps

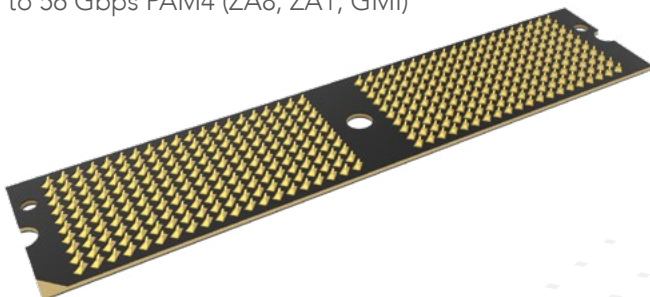
LPAM/LPAF



ALSO AVAILABLE: HIGH-DENSITY SOLUTIONS

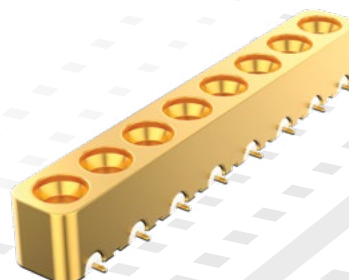
COMPRESSION INTERPOSERS

Body heights down to 1 mm and performance to 56 Gbps PAM4 (ZA8, ZA1, GMI)



PRECISION RF BOARD-TO-BOARD SOLUTIONS

SMP, SMPM and Ganged SMPM with a push-on design for quick installation and frequency to 65 GHz (GPPC, GPPB, SMPM, PRFIA, SMP).





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